



# PMV170EPA

80 V, P-channel Trench MOSFET

1 October 2025

Product data sheet

## 1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in a small SOT23 Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

## 2. Features and benefits

- Logic-level compatible
- Very fast switching
- Trench MOSFET technology
- Extended temperature range  $T_j = 175\text{ °C}$
- AEC-Q101 qualified

## 3. Applications

- Relay driver
- High-speed line driver
- High-side load switch
- Switching circuits

## 4. Quick reference data

Table 1. Quick reference data

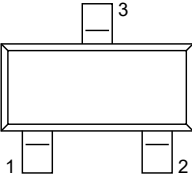
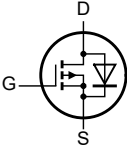
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$25\text{ °C} \leq T_j \leq 175\text{ °C}$		-	-	-80	V
$V_{GS}$	gate-source voltage	$T_j = 25\text{ °C}$	[1]	-20	-	20	V
$I_D$	drain current	$V_{GS} = -10\text{ V}; T_{amb} = 25\text{ °C}$	[2]	-	-	-1.6	A
<b>Static characteristics</b>							
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = -10\text{ V}; I_D = -1.6\text{ A}; T_j = 25\text{ °C}$		-	170	225	mΩ

[1] See application note AN90001.

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain  $6\text{ cm}^2$ .

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 SOT23	 017aaa094
2	S	source		
3	D	drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMV170EPA	SOT23	plastic, surface-mounted package; 3 terminals; 1.9 mm pitch; 2.9 mm x 1.3 mm x 1 mm body	SOT23

7. Marking

Table 4. Marking codes

Type number	Marking code[1]
PMV170EPA	XZ%

[1] % = placeholder for manufacturing site code

## 8. Limiting values

**Table 5. Limiting values**

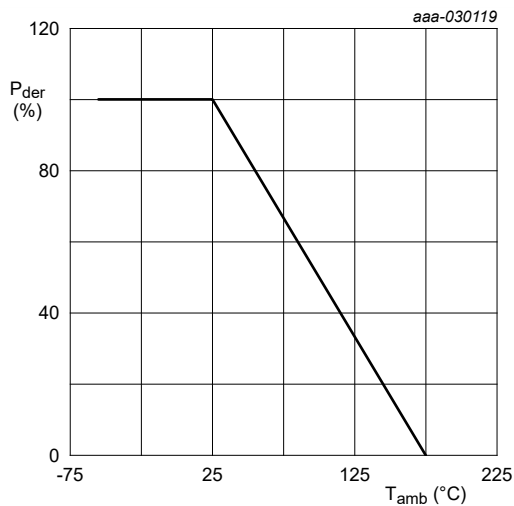
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DS}$	drain-source voltage	$25\text{ }^{\circ}\text{C} \leq T_j \leq 175\text{ }^{\circ}\text{C}$		-	-80	V
$V_{GS}$	gate-source voltage	$T_j = 25\text{ }^{\circ}\text{C}$	[1]	-20	20	V
$I_D$	drain current	$V_{GS} = -10\text{ V}; T_{amb} = 25\text{ }^{\circ}\text{C}$	[2]	-	-1.6	A
		$V_{GS} = -10\text{ V}; T_{amb} = 100\text{ }^{\circ}\text{C}$	[2]	-	-1.1	A
$I_{DM}$	peak drain current	$T_{amb} = 25\text{ }^{\circ}\text{C}$ ; single pulse; $t_p \leq 10\text{ }\mu\text{s}$		-	-16	A
$P_{tot}$	total power dissipation	$T_{amb} = 25\text{ }^{\circ}\text{C}$	[3]	-	630	mW
			[2]	-	1.3	W
		$T_{sp} = 25\text{ }^{\circ}\text{C}$		-	8.3	W
$T_j$	junction temperature			-55	175	$^{\circ}\text{C}$
$T_{amb}$	ambient temperature			-55	175	$^{\circ}\text{C}$
$T_{stg}$	storage temperature			-65	175	$^{\circ}\text{C}$
<b>Source-drain diode</b>						
$I_S$	source current	$T_{amb} = 25\text{ }^{\circ}\text{C}$	[2]	-	-1.2	A
<b>Avalanche ruggedness</b>						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$ ; $I_D = -1\text{ A}$ ; DUT in avalanche (unclamped)		-	42	mJ

[1] See application note AN90001.

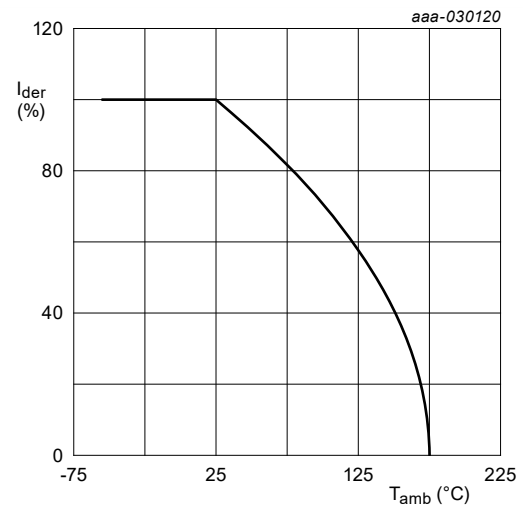
[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain  $6\text{ cm}^2$ .

[3] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.



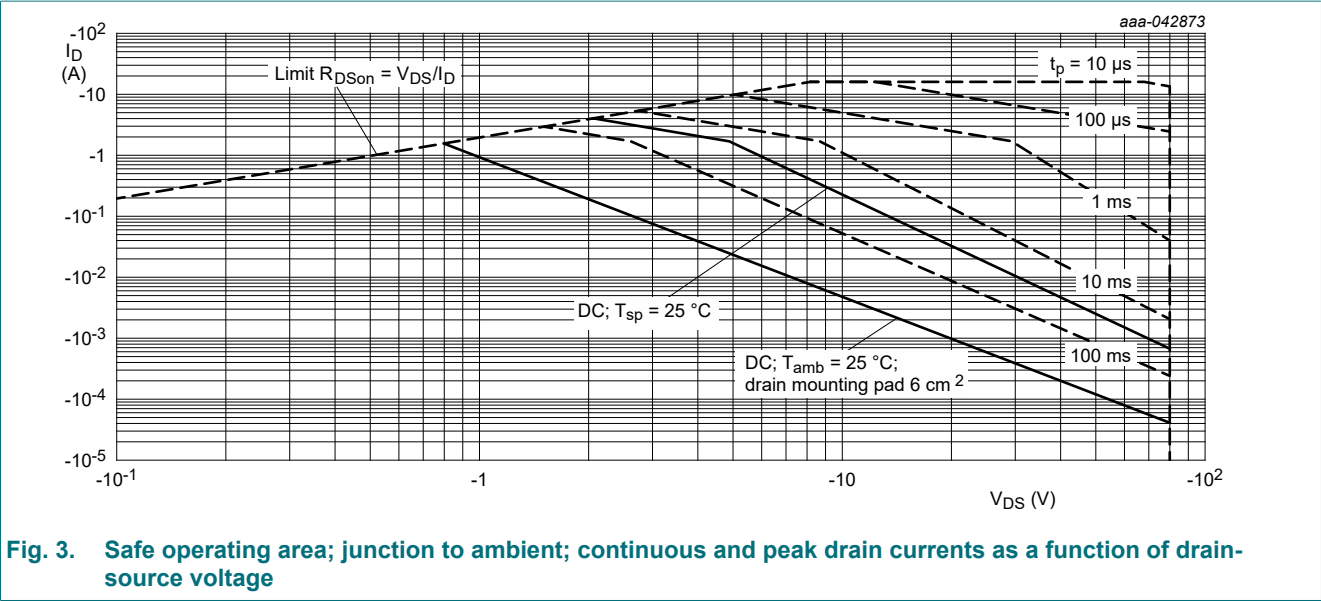
$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}\text{C})}} \times 100\%$$

**Fig. 1. Normalized total power dissipation as a function of ambient temperature**



$$I_{der} = \frac{I_D}{I_{D(25^{\circ}\text{C})}} \times 100\%$$

**Fig. 2. Normalized continuous drain current as a function of ambient temperature**



9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	195	240	K/W
			[2]	-	100	120	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	13	18	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.  
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.

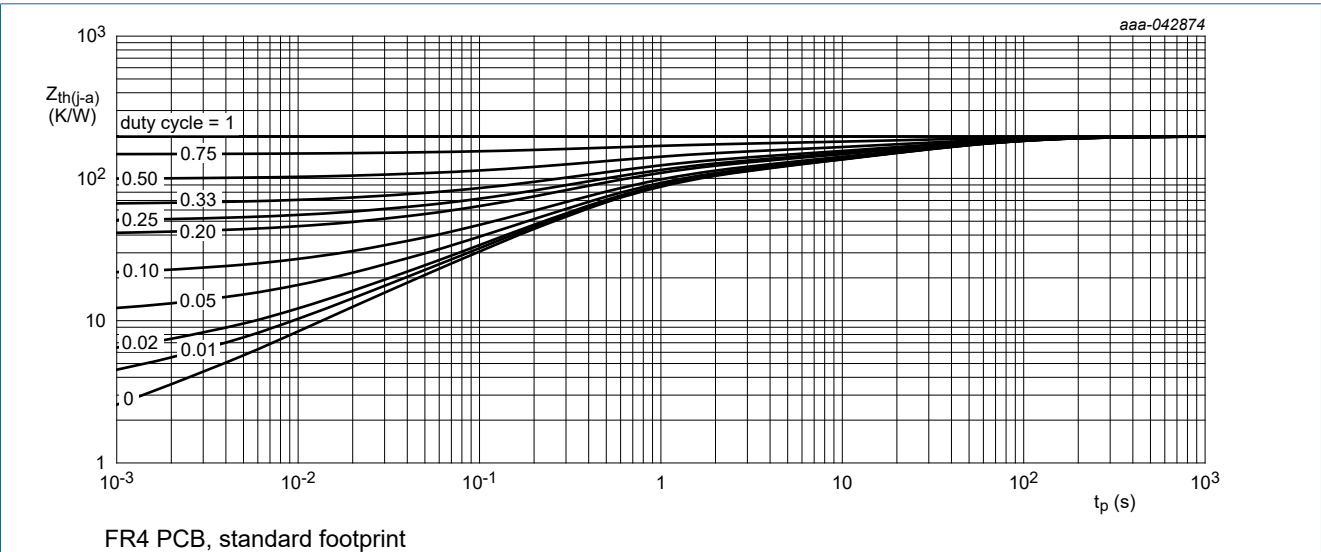


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

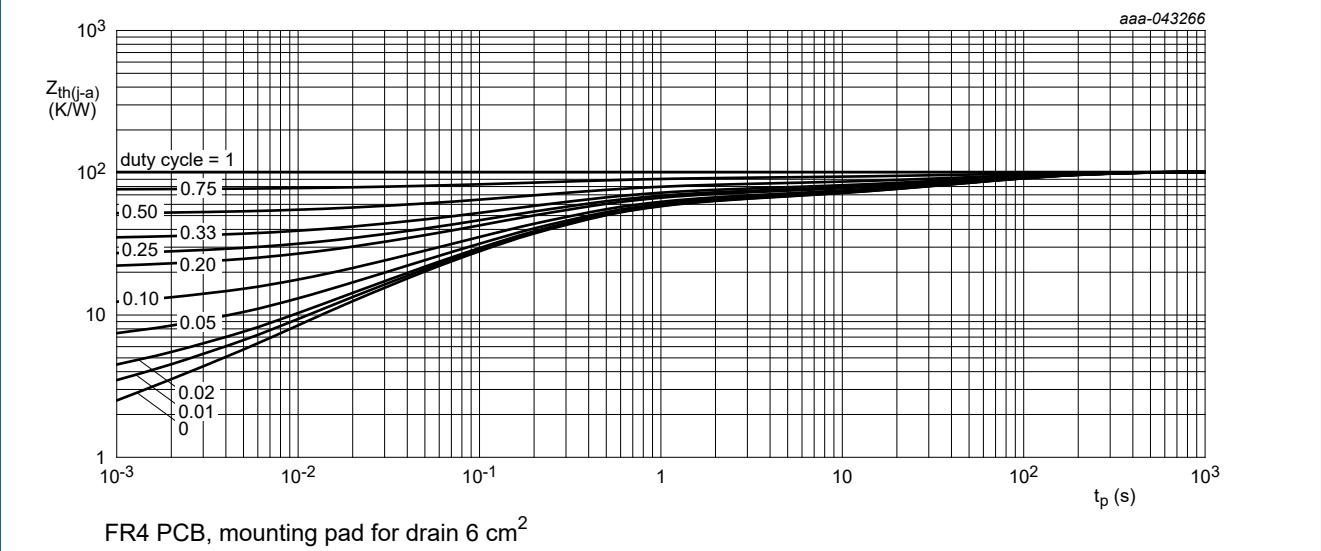


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	I <sub>D</sub> = -250 μA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		-80	-	-	V
V <sub>GSth</sub>	gate-source threshold voltage	I <sub>D</sub> = -250 μA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = 25 °C		-1.4	-2	-2.7	V
I <sub>DSS</sub>	drain leakage current	V <sub>DS</sub> = -80 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	-	-1	μA
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = -20 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	-	-100	nA
		V <sub>GS</sub> = 20 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	-	100	nA
R <sub>DSon</sub>	drain-source on-state resistance	V <sub>GS</sub> = -10 V; I <sub>D</sub> = -1.6 A; T <sub>j</sub> = 25 °C		-	170	225	mΩ
		V <sub>GS</sub> = -10 V; I <sub>D</sub> = -1.6 A; T <sub>j</sub> = 175 °C		-	380	510	mΩ
		V <sub>GS</sub> = -4.5 V; I <sub>D</sub> = -1.5 A; T <sub>j</sub> = 25 °C		-	200	270	mΩ
g <sub>fs</sub>	forward transconductance	V <sub>DS</sub> = -5 V; I <sub>D</sub> = -1.6 A; T <sub>j</sub> = 25 °C		-	4.8	-	S
R <sub>G</sub>	gate resistance	f = 1 MHz		-	10.5	-	Ω
Dynamic characteristics							
Q <sub>G(tot)</sub>	total gate charge	V <sub>DS</sub> = -40 V; I <sub>D</sub> = -1.6 A; V <sub>GS</sub> = -10 V; T <sub>j</sub> = 25 °C		-	10	15	nC
Q <sub>GS</sub>	gate-source charge			-	1.7	-	nC
Q <sub>GD</sub>	gate-drain charge			-	2.3	-	nC
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = -40 V; f = 1 MHz; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	535	-	pF
C <sub>oss</sub>	output capacitance			-	30	-	pF
C <sub>rss</sub>	reverse transfer capacitance			-	19	-	pF
t <sub>d(on)</sub>	turn-on delay time	V <sub>DS</sub> = -40 V; I <sub>D</sub> = -1.6 A; V <sub>GS</sub> = -10 V; R <sub>G(ext)</sub> = 6 Ω; T <sub>j</sub> = 25 °C		-	3	-	ns
t <sub>r</sub>	rise time			-	4	-	ns
t <sub>d(off)</sub>	turn-off delay time			-	22	-	ns
t <sub>f</sub>	fall time			-	26	-	ns
Source-drain diode							
V <sub>SD</sub>	source-drain voltage	I <sub>S</sub> = -1.2 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	-0.7	-1.2	V
t <sub>rr</sub>	reverse recovery time	I <sub>S</sub> = -1.2 A; dI <sub>S</sub> /dt = 100 A/μs; V <sub>GS</sub> = 0 V; V <sub>DS</sub> = -40 V; T <sub>j</sub> = 25 °C		-	19	-	ns
Q <sub>r</sub>	recovered charge			-	14	-	nC

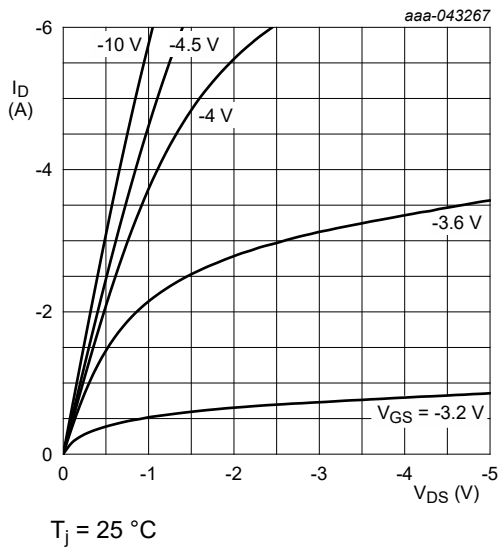


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

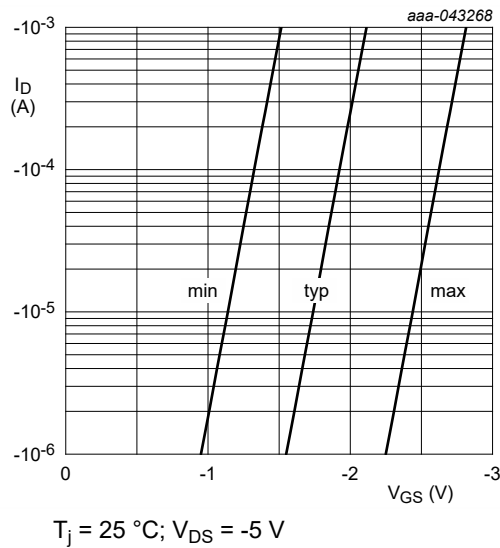


Fig. 7. Subthreshold drain current as a function of gate-source voltage

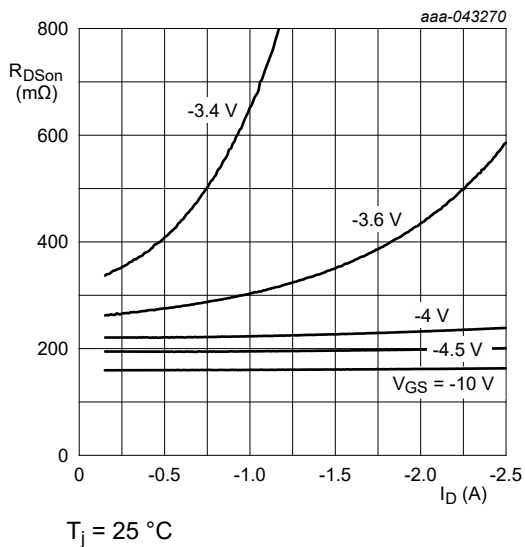


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

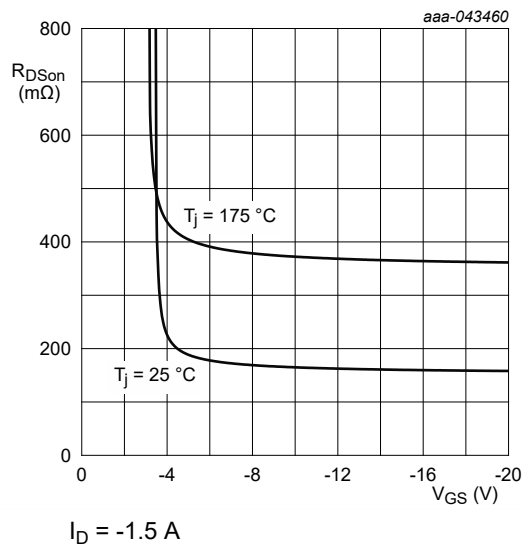


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

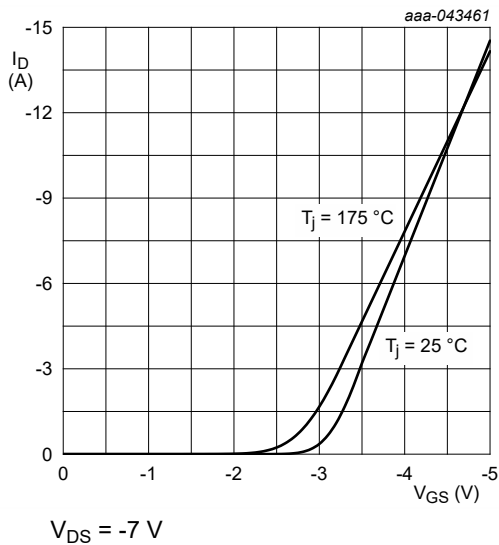


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

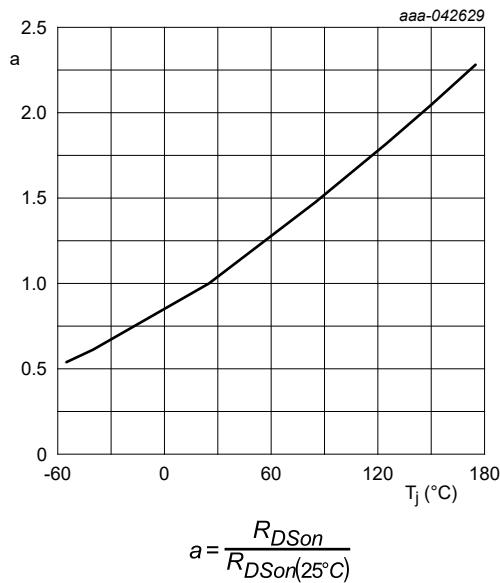


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

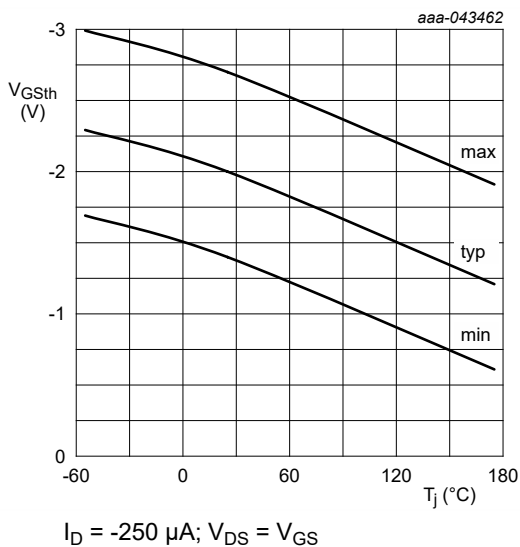


Fig. 12. Gate-source threshold voltage as a function of junction temperature

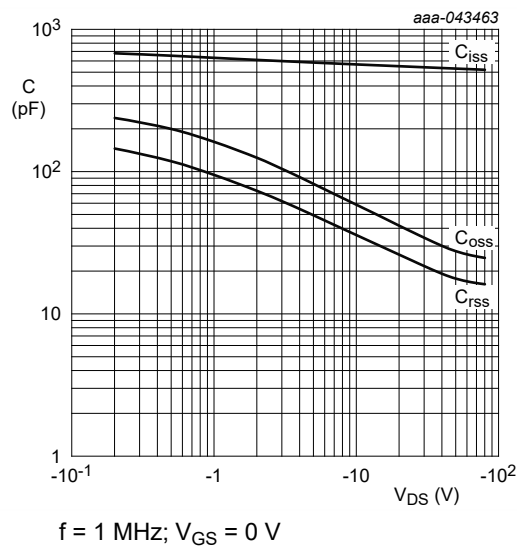


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



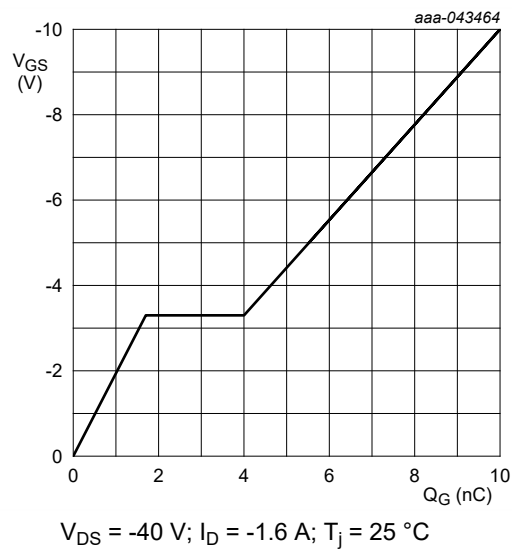


Fig. 14. Gate-source voltage as a function of gate charge; typical values

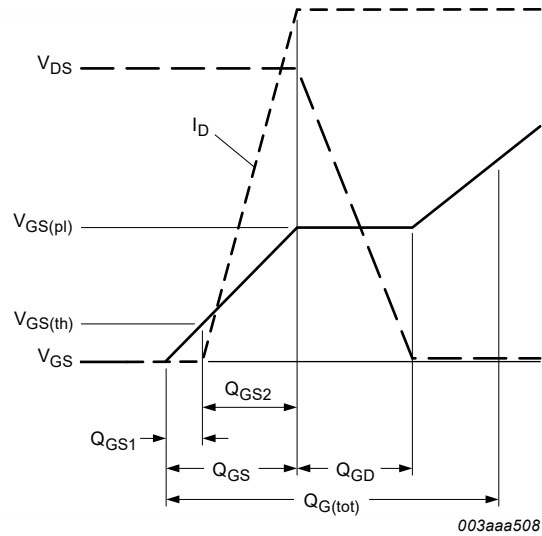


Fig. 15. Gate charge waveform definitions

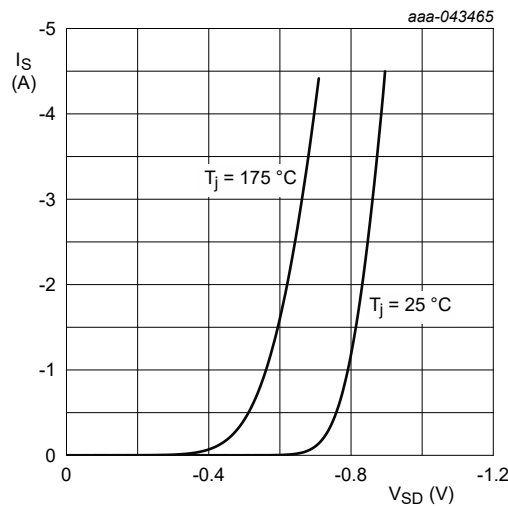


Fig. 16. Source current as a function of source-drain voltage; typical values

## 11. Test information

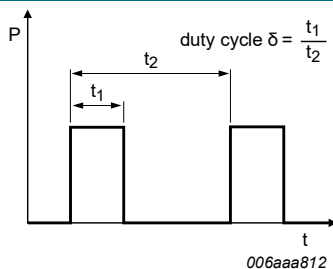
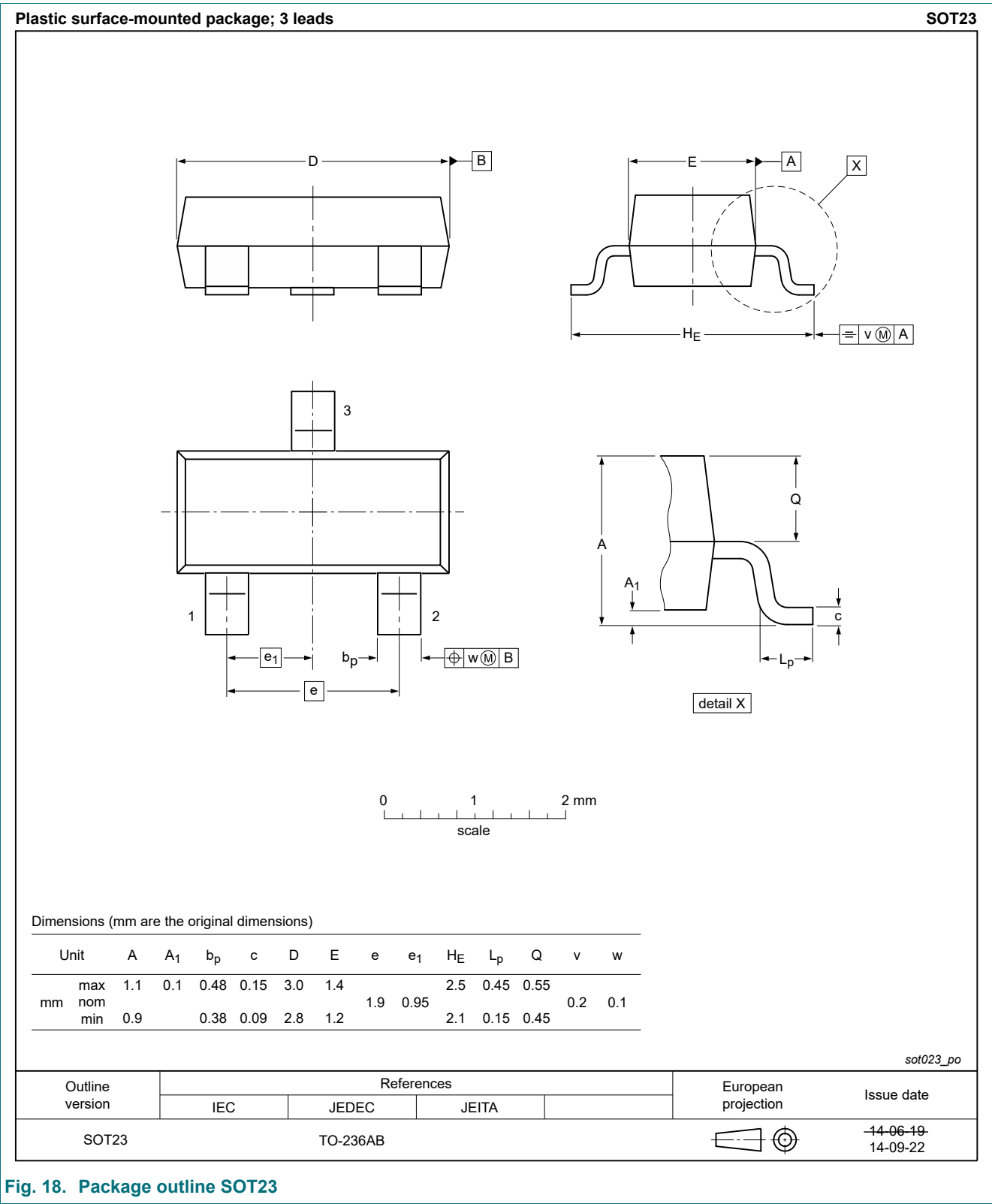


Fig. 17. Duty cycle definition

### Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline



13. Soldering



Fig. 19. Reflow soldering footprint for SOT23

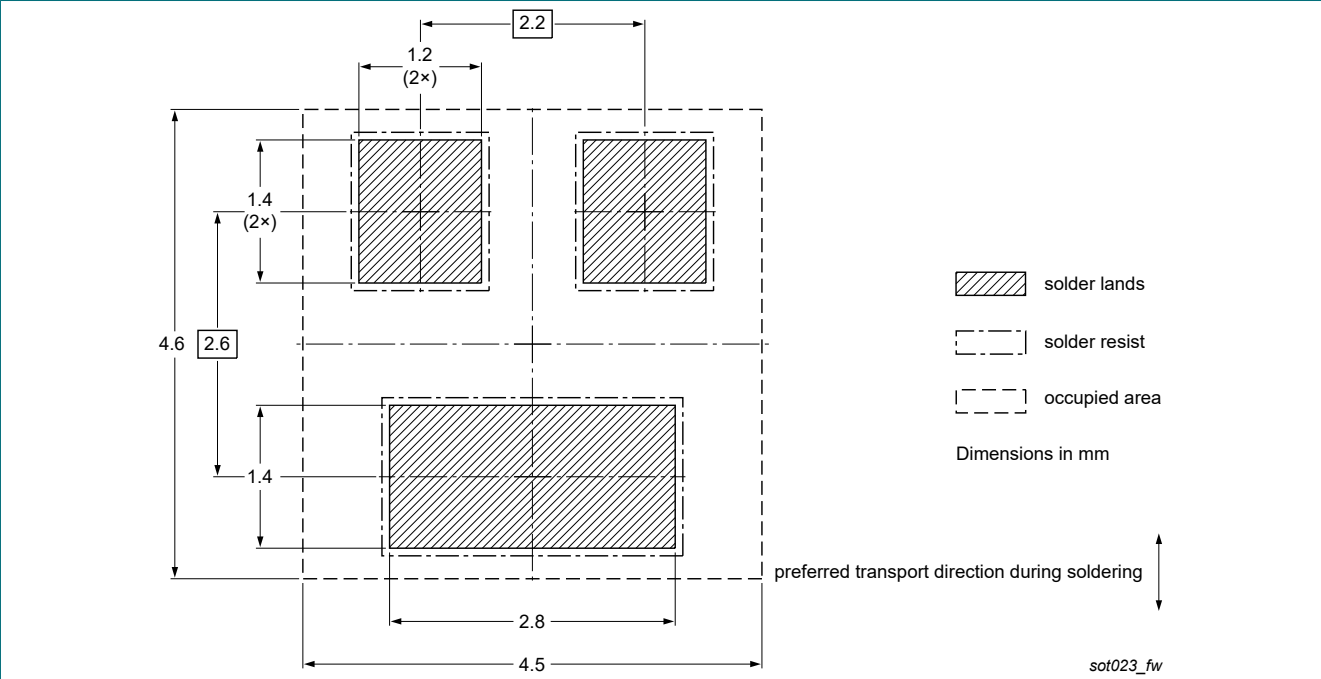


Fig. 20. Wave soldering footprint for SOT23

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMV170EPA v.1	20251001	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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